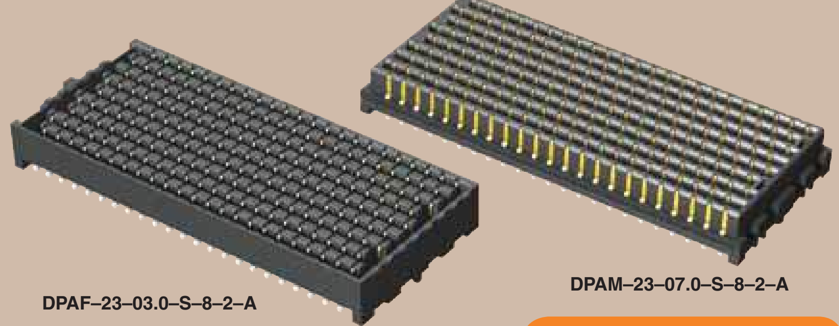

DPAF–23–03.0–S–8–2–A

DPAM–23–07.0–S–8–2–A

(2,16 mm) .085"

DPAM, DPAF SERIES

HIGH DENSITY DIFFERENTIAL PAIR ARRAY

DPAM Mates with: DPAF

DPAF Mates with: DPAM

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?DPAM or www.samtec.com?DPAF

Insulator Material: Black LCP
Contact Material: Copper Alloy
Plating: Au over 50μ" (1,27 μm) Ni
Current Rating (2x3): 2.9 A per pin
Operating Temp Range: -55°C to +125°C
Contact Resistance: 10.4mΩ
Working Voltage: 300 VAC
Mated Cycles: 100 Cycles
RoHS Compliant: Yes
Lead-Free Solderable: Yes

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

Protocols Supported

- Fibre Channel
- Rapid I/O
- PCI Express®
- SATA
- InfiniBand™
- XAUI
- MGT (Rocket I/O)

Download app notes at www.samtec.com/appnote
Contact SIG @ samtec.com for questions on protocols

ALSO AVAILABLE
(MOQ Required)

- Tin-Lead Solder Charge
- Other platings

Contact Samtec.

Note: Patented

Note: Some sizes, styles and options are non-standard, non-returnable.

DPAM – PAIRS PER ROW – 07.0 – PLATING OPTION – NO. OF ROWS – SOLDER TYPE – A – OPTION

PAIRS PER ROW: –04, –06, –08, –15, –23

PLATING OPTION: –S =30μ" (0,76 μm) Gold on contact area, Tin on solder tail

NO. OF ROWS:
- –8 =Eight Pair Rows
- –3 =Three Pair Rows

SOLDER TYPE: –2 = Lead-Free Tin Alloy 96.5% Sn/ 3% Ag/.5% Cu Solder Crimp

OPTION:
- –K =(20,00 mm) 0.80" DIA Polyimide film Pick & Place Pad
- –TR =Tape & Reel
- –GP =Guide Post (–23 only)

Final Inch® CERTIFIED

Perimeter Grounds (TYP); G1; (2,54) .100; A; 02 01 G2 03 04; Signal Pairs (TYP); (2,54) .100

No. of positions x (2,16) .085 + (4,34) .171; (6,66) .262; (0,13) .005; (2,16) .085; (1,08) .0425; (1,27) .050 DIA; (1,27) .050; No. of positions x (2,16) .085 + (2,95) .116

NO OF ROWS	A
–8	(24,59) .968
–3	(11,89) .468

DPAM/DPAF 10 mm Stack Height	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	8 GHz / 16 Gbps
Differential Pair Signaling	7 GHz / 14 Gbps

*Performance data includes effects of a non-optimized PCB.

Complete test data available at www.samtec.com?DPAM, www.samtec.com?DPAF or contact sig@samtec.com

DPAF – PAIRS PER ROW – 03.0 – PLATING OPTION – NO. OF ROWS – SOLDER TYPE – A – OPTION

PAIRS PER ROW: –04, –06, –08, –15, –23

PLATING OPTION: –S =30μ" (0,76 μm) Gold on contact area, Tin on solder tail

NO. OF ROWS:
- –8 =Eight Pair Rows
- –3 =Three Pair Rows

SOLDER TYPE: –2 = Lead-Free Tin Alloy 96.5% Sn/ 3%Ag/ .5% Cu Solder Crimp

OPTION:
- –K =(20,00 mm) 0.80" DIA Polyimide film Pick & Place Pad
- –TR =Tape & Reel

No. of positions x (2,16) .085 + (4,34) .171; G1; Signal Pairs (TYP); A; (1,52) .060; (1,27) .050; 04; 02; 01; (2,54) .100; G2; 03; Perimeter Grounds (TYP)

(6,45) .254; (0,13) .005; (2,16) .085; (1,08) .0425; Solder crimped on tail; (1,27) .050 DIA; (1,27) .050; No. of positions x (2,16) .085 + (2,95) .116

NO OF ROWS	A
–8	(23,32) .918
–3	(10,62) .418

DPAM LEAD STYLE	DPAF MATED HEIGHT* –03.0
–07.0	10 mm

*Processing conditions will affect mated height.

SIZE	USABLE PAIRS PER ARRAY*
–04 x –3	6 Pairs
–06 x –3	12 Pairs
–04 x –8	16 Pairs
–06 x –8	32 Pairs
–08 x –8	48 Pairs
–15 x –8	104 Pairs
–23 x –8	168 Pairs
–08 x –3	18 Pairs
–15 x –3	39 Pairs
–23 x –3	63 Pairs

*Assumes first and last pair in each row are grounded

Due to technical progress, all designs, specifications and components are subject to change without notice.